

IN THE CLAIMS:

The status of each claim that has been introduced in the above-referenced application is identified in the ensuing listing of the claims. This listing of the claims replaces all previously submitted claims listings.

1. (Currently amended) A semiconductor device component, comprising:
a substrate having a surface with contact pads exposed thereto; and
at least one stabilizer protruding from saidthe surface and positioned between a periphery of
saidthe surface and each contact pad exposed to saidthe surface and including a plurality
of at least partially superimposed, contiguous, mutually adhered layers of the same type
of dielectric material.
2. (Currently amended) The semiconductor device component of claim 1, wherein
saidthe at least one stabilizer protrudes from saidthe surface a distance no more than a distance
that at least one conductive structure to be disposed in contact with at least one of saidthe contact
pads will extend beyond saidthe surface.
3. (Currently amended) The semiconductor device component of claim 2, wherein
saidthe at least one stabilizer protrudes from saidthe surface a distance that permits conductive
structures on saidthe contact pads to contact conductors of another semiconductor device
component upon assembly of saidthe substrate with saidthe another semiconductor device
component such that saidthe surface of saidthe assembly faces a conductor-bearing surface of
saidthe another semiconductor device component.
4. (Canceled)
5. (Currently amended) The semiconductor device component of claim 1, wherein
saidthe at least one stabilizer comprises a photocurable material.

6. (Canceled)

7. (Currently amended) The semiconductor device component of claim 1, wherein saidthe at least one stabilizer is positioned proximate a corner of saidthe surface.

8. (Currently amended) The semiconductor device component of claim 1, wherein saidthe at least one stabilizer has a cross-sectional shape of one of quadrilateral, round, oval, and triangular.

9. (Currently amended) The semiconductor device component of claim 1, wherein saidthe at least one stabilizer is elongated in a direction parallel to saidthe surface.

10. (Currently amended) The semiconductor device component of claim 1, further comprising protruding conductive structures in contact with selected ones of saidthe contact pads.

11. (Currently amended) The semiconductor device component of claim 10, wherein saidthe conductive structures comprise at least one of solder bumps, conductive columns, conductor-filled columns, and z-axis conductive adhesive.

12. (Currently amended) The semiconductor device component of claim 1, wherein saidthe substrate comprises a semiconductor wafer with a plurality of dice thereon.

13. (Currently amended) A semiconductor device component, comprising:
a substrate having a surface with contact pads exposed thereto, saidthe contact pads being
configured to be connected with conductors on a surface of another semiconductor device
component; and
at least one stabilizer protruding from saidthe surface of saidthe substrate and positioned between
a periphery of saidthe surface and saidthe contact pads, saidthe at least one stabilizer

comprising a plurality of superimposed, contiguous, mutually adhered layers, each of which comprises dielectric material.

14. (Currently amended) The semiconductor device component of claim 13, wherein saidthe at least one stabilizer protrudes from saidthe surface of saidthe substrate a distance no more than a distance that at least one conductive structure to be disposed in contact with at least one of saidthe contact pads will extend beyond saidthe surface.

15. (Currently amended) The semiconductor device component of claim 14, wherein saidthe at least one stabilizer protrudes from saidthe surface of saidthe substrate a distance that permits conductive structures on saidthe contact pads to contact saidthe conductors of saidthe another semiconductor device component.

16. (Currently amended) The semiconductor device component of claim 13, wherein saidthe at least one stabilizer comprises a dielectric material.

17. (Currently amended) The semiconductor device component of claim 13, wherein saidthe at least one stabilizer comprises a photocurable material.

18. (Currently amended) The semiconductor device component of claim 13, wherein saidthe at least one stabilizer is positioned proximate a corner of saidthe surface of saidthe substrate.

19. (Currently amended) The semiconductor device component of claim 13, wherein saidthe at least one stabilizer has a cross-sectional shape of one of quadrilateral, round, oval, and triangular.

20. (Currently amended) The semiconductor device component of claim 13, wherein saidthe at least one stabilizer is elongated in a direction parallel to saidthe surface.

21. (Currently amended) The semiconductor device component of claim 13, further comprising protruding conductive structures in contact with selected ones of saidthe contact pads.

22. (Currently amended) The semiconductor device component of claim 21, wherein saidthe conductive structures comprise at least one of solder bumps, conductive columns, conductor-filled columns, and z-axis conductive adhesive.

23. (Currently amended) The semiconductor device component of claim 13, wherein saidthe substrate comprises a semiconductor wafer with a plurality of dice thereon.

24. (Currently amended) The semiconductor device component of claim 13, wherein saidthe at least one stabilizer maintains a substantially uniform distance between saidthe surface of saidthe substrate and saidthe surface of saidthe another semiconductor device component.

25. (Currently amended) A semiconductor device component, comprising:
a substrate having a surface with contact pads exposed thereto, saidthe contact pads being
configured to be connected with conductors on a first surface of another semiconductor
device component, each contact pad of the semiconductor device component being
arranged substantially in-line with a plurality of other contact pads and positioned
proximate to a center line of saidthe substrate; and
at least one nonconductive stabilizer protruding from saidthe surface of saidthe substrate and
positioned between a periphery of saidthe surface and saidthe contact pads, saidthe at
least one nonconductive stabilizer comprising an elongate element which extends in a
direction parallel to saidthe surface of saidthe substrate.

26. (Currently amended) The semiconductor device component of claim 25, wherein saidthe at least one stabilizer is configured so that voids do not occur in an insulative underfill

material when saidthe insulative underfill material is flowed into a space created when saidthe substrate is connected with saidthe another semiconductor device component.

27. (Currently amended) The semiconductor device component of claim 25, wherein saidthe at least one stabilizer protrudes from saidthe surface of saidthe substrate a distance no more than a distance that at least one conductive structure to be disposed in contact with at least one of saidthe contact pads will extend beyond saidthe surface.

28. (Currently amended) The semiconductor device component of claim 27, wherein saidthe at least one stabilizer protrudes from saidthe surface a distance that permits conductive structures on saidthe contact pads to contact saidthe conductors of saidthe another semiconductor device component.

29. (Currently amended) The semiconductor device component of claim 25, wherein saidthe at least one stabilizer comprises a dielectric material.

30. (Currently amended) The semiconductor device component of claim 25, wherein saidthe at least one stabilizer comprises a photocurable material.

31. (Currently amended) A semiconductor device component, comprising:
a substrate having a surface with contact pads exposed thereto, the contact pads being arranged substantially in-line with one another and positioned proximate to a center line of the substrate; and
at least one stabilizer protruding from saidthe surface, comprising an elongate structure which extends in a direction parallel to a plane of saidthe surface, and being positioned between a periphery of saidthe surface and saidall of the contact pads.

32. (Canceled)